

パワーモジュール専用封止材

Special Molding Compound for power control module

SiC/GaNパワーモジュールへの採用により更なる小型・軽量化に貢献

Adopting to Power Control Module contributes to Further Miniaturization and Lightweight

特長

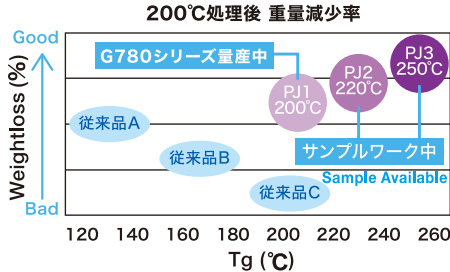
Advantage

優れた絶縁・放熱・耐熱・高密着のパワーモジュール用封止材

Excellent properties (insulation, heat dissipation, heat resistance, and adhesiveness) contribute to miniaturization and high performance.

高耐熱性 High Heat Resistance

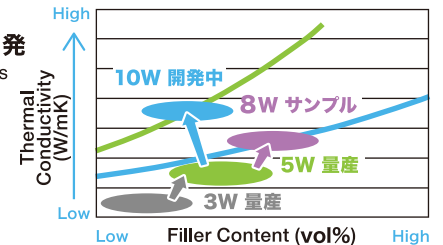
**SiC/GaN
対応材の開発**
Development of
SiC / GaN
compatible material



高放熱性 High Heat Dissipation

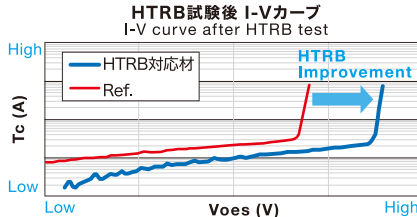
**5W材の量産開始
8W材・10W材を開発**

5W material is started mass
production
For 8W and 10W is under
development



高信頼性 High Reliability

HTRB対応材の開発
Development of HTRB
compatible material



Test PKG : TO-247

高絶縁性 High Insulation Resistance

**高CTI(耐トラッキング指数)化
による沿面距離の
短縮実現**

Creeping distance becomes
shorter by high CTI

